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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	80 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c554-20-so

Special Microcontroller Features:

- Power-on Reset (POR)
- Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Watchdog Timer (WDT) with its own on-chip RC oscillator for reliable operation
- Programmable code protection
- · Power saving SLEEP mode
- · Selectable oscillator options
- Serial in-circuit programming (via two pins)
- Four user programmable ID locations

Note: For additional information on enhancements, see Appendix A

CMOS Technology:

- Low power, high speed CMOS EPROM technology
- · Fully static design
- Wide operating voltage range
 - 2.5V to 5.5V
- Commercial, Industrial and Extended temperature range
- Low power consumption
 - < 2.0 mA @ 5.0V, 4.0 MHz
 - 15 μA typical 3.0V, 32 kHz
 - < 1.0 μ A typical standby current @ 3.0V

Device Differences

Device	Voltage Range	Oscillator
PIC16C554	2.5 - 5.5	(Note 1)
PIC16C557	2.5 - 5.5	(Note 1)
PIC16C558	2.5 - 5.5	(Note 1)

Note 1: If you change from this device to another device, please verify oscillator characteristics in your application.

TABLE 1-1: PIC16C55X FAMILY OF DEVICES

		PIC16C554	PIC16C557	PIC16C558
Clock	Maximum Frequency of Operation (MHz)	20	20	20
Memory	EPROM Program Memory (x14 words)	512	2K	2K
	Data Memory (bytes)	80	128	128
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0
	Interrupt Sources	3	3	3
	I/O Pins	13	22	13
Features	Voltage Range (Volts)	2.5-5.5	2.5-5.5	2.5-5.5
· oatai oo	Brown-out Reset	_	_	_
	Packages	18-pin DIP, SOIC; 20-pin SSOP	28-pin DIP, SOIC; 28-pin SSOP	18-pin DIP, SOIC, SSOP

All PIC® Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C55X Family devices use serial programming with clock pin RB6 and data pin RB7.

FIGURE 3-1: BLOCK DIAGRAM

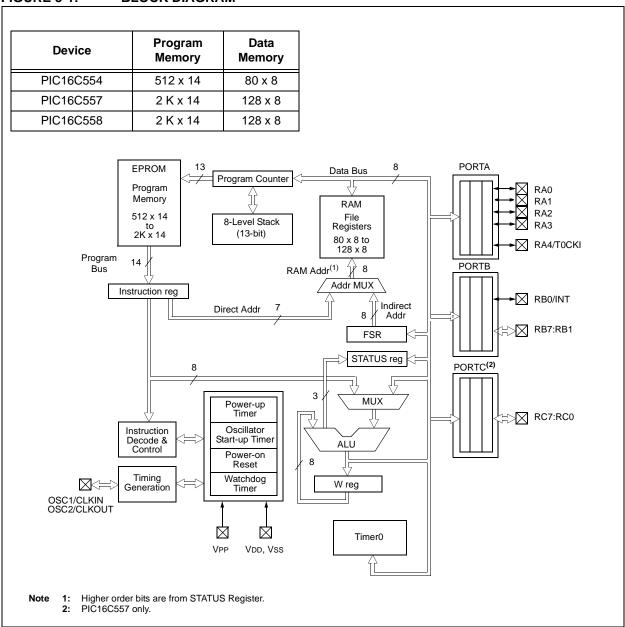


TABLE 3-1: PIC16C55X PINOUT DESCRIPTION

		Pin Numb	er	Pin	Buffer	
Name	PDIP	SOIC	SSOP	Туре	Туре	Description
OSC1/CLKIN	16	16	18	I	ST/CMOS	Oscillator crystal input/external clock source output.
OSC2/CLKOUT	15	15	17	0	_	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
MCLR/VPP	4	4	4	I/P	ST	Master clear (Reset) input/programming voltage input. This pin is an active low RESET to the device.
RA0	17	17	19	I/O	ST	Bi-directional I/O port
RA1	18	18	20	I/O	ST	Bi-directional I/O port
RA2	1	1	1	I/O	ST	Bi-directional I/O port
RA3	2	2	2	I/O	ST	Bi-directional I/O port
RA4/T0CKI	3	3	3	I/O	ST	Bi-directional I/O port or external clock input for TMR0. Output is open drain type.
RB0/INT	6	6	7	I/O	TTL/ST ⁽¹⁾	Bi-directional I/O port can be software programmed for internal weak pull-up. RB0/INT can also be selected as an external interrupt pin.
RB1	7	7	8	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up.
RB2	8	8	9	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up.
RB3	9	9	10	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up.
RB4	10	10	11	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up. Interrupt-on-change pin.
RB5	11	11	12	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up. Interrupt-on-change pin.
RB6	12	12	13	I/O	TTL/ST ⁽²⁾	Bi-directional I/O port can be software programmed for internal weak pull-up. Interrupt-on-change pin. Serial programming clock.
RB7	13	13	14	I/O	TTL/ST ⁽²⁾	Bi-directional I/O port can be software programmed for internal weak pull-up. Interrupt-on-change pin. Serial programming data.
RC0 ⁽³⁾	18	18	18	I/O	TTL	Bi-directional I/O port input buffer.
RC1 ⁽³⁾	19	19	19	I/O	TTL	Bi-directional I/O port input buffer.
RC2 ⁽³⁾	20	20	20	I/O	TTL	Bi-directional I/O port input buffer.
RC3 ⁽³⁾	21	21	21	I/O	TTL	Bi-directional I/O port input buffer.
RC4 ⁽³⁾	22	22	22	I/O	TTL	Bi-directional I/O port input buffer.
RC5 ⁽³⁾	23	23	23	1/0		Bi-directional I/O port input buffer.
RC6 ⁽³⁾					TTL	· ·
	24	24	24	I/O	TTL	Bi-directional I/O port input buffer.
RC7 ⁽³⁾	25	25	25	I/O	TTL	Bi-directional I/O port input buffer.
Vss	5	5	5,6	Р	_	Ground reference for logic and I/O pins.
VDD	14	14	15,16	P O = Input	_	Positive supply for logic and I/O pins.

Legend:

O = Output

I/O = Input/output

P = Power

— = Not used TTL = TTL input I = Input

ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.

2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.

3: PIC16C557 only.

TABLE 4-1: SPECIAL REGISTERS FOR THE PIC16C55X

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Detail on Page:
Bank 0											
00h	INDF	Addressi physical	ing this loca register)	ation uses	contents	of FSR to	address d	ata memo	ory (not a	xxxx xxxx	21
01h	TMR0	Timer0 N	/lodule's Re	egister						xxxx xxxx	47
02h	PCL	Program	Counter's	(PC) Leas	t Significa	int Byte				0000 0000	21
03h	STATUS	IRP ⁽²⁾	RP1 ⁽²⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	17
04h	FSR	Indirect of	data memo	ry address	s pointer				I.	xxxx xxxx	21
05h	PORTA	_	_	_	RA4	RA3	RA2	RA1	RA0	x xxxx	23
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	25
07h	PORTC ⁽⁴⁾	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	27
08h	_	Unimple	mented	l.						_	_
09h	_	Unimple	mented							_	_
0Ah	PCLATH	_	_	_	Write but	ffer for up	per 5 bits	of progran	n counter	0 0000	21
0Bh	INTCON	GIE	(3)	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	19
0Ch	_	Unimplei	mented							_	_
0Dh-1Eh	_	Unimple	mented								1
1Fh	_	Unimple	mented							_	_
Bank 1											
80h	INDF	Addressi physical	ing this loca register)	ation uses	contents	of FSR to	address d	ata memo	ory (not a	xxxx xxxx	21
81h	OPTION	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	18
82h	PCL	Program	Counter's	(PC) Leas	t Significa	int Byte				0000 0000	21
83h	STATUS	_	_	RP0	TO	PD	Z	DC	С	0001 1xxx	17
84h	FSR			Indirect d	ata memo	ry addres	s pointer		I	xxxx xxxx	21
85h	TRISA	_	_	_	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	23
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	25
87h	TRISC ⁽⁴⁾	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	27
88h	_	Unimple	mented	l.					I	_	_
89h	_	Unimple	mented							_	
8Ah	PCLATH	_	_	_	Write but	ffer for up	per 5 bits	of progran	n counter	0 0000	21
8Bh	INTCON	GIE	(3)	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	19
8Ch	_	Unimplei	mented							_	_
8Dh	_	Unimple	mented							_	
8Eh	PCON	_	_	_	_	_	_	POR	_	0-	20
8Fh-9Eh	_	Unimple	mented							_	_
		_	mented								

Legend: — = Unimplemented locations read as '0', u = unchanged, x = unknown, q = value depends on condition, shaded = unimplemented

Note 1: Other (non Power-up) Resets include MCLR Reset and Watchdog Timer Reset during normal operation.

^{2:} IRP & RP1 bits are reserved, always maintain these bits clear.

^{3:} Bit 6 of INTCON register is reserved for future use. Always maintain this bit as clear.

^{4:} PIC16C557 only.

5.0 I/O PORTS

The PIC16C554 and PIC16C558 have two ports, PORTA and PORTB. The PIC16C557 has three ports, PORTA, PORTB and PORTC.

5.1 PORTA and TRISA Registers

PORTA is a 5-bit wide latch. RA4 is a Schmitt Trigger input and an open-drain output. Port RA4 is multiplexed with the T0CKI clock input. All other RA port pins have Schmitt Trigger input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers) which can configure these pins as input or output.

A '1' in the TRISA register puts the corresponding output driver in a Hi-impedance mode. A '0' in the TRISA register puts the contents of the output latch on the selected pin(s).

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

Note 1: On RESET, the TRISA register is set to all inputs.

FIGURE 5-1: BLOCK DIAGRAM OF PORT PINS RA<3:0>

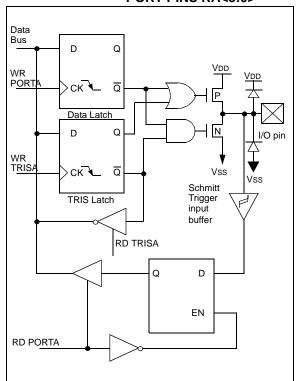
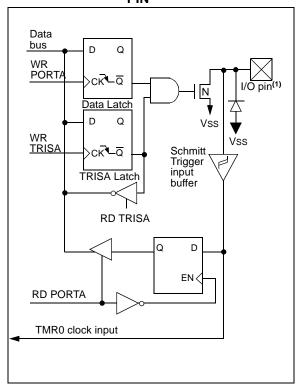


FIGURE 5-2: BLOCK DIAGRAM OF RA4



6.0 SPECIAL FEATURES OF THE CPU

What sets a microcontroller apart from other processors are special circuits to deal with the needs of real-time applications. The PIC16C55X family has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection.

These are:

- 1. OSC selection
- 2. RESET
- 3. Power-on Reset (POR)
- 4. Power-up Timer (PWRT)
- 5. Oscillator Start-Up Timer (OST)
- 6. Interrupts
- 7. Watchdog Timer (WDT)
- 8. SLEEP
- 9. Code protection
- 10. ID Locations
- 11. In-circuit serial programming™

The PIC16C55X has a Watchdog Timer which is controlled by configuration bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), which is intended to keep the chip in RESET until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only, designed to keep the part in RESET while the power supply stabilizes. With these two functions on-chip, most applications need no external RESET circuitry.

The SLEEP mode is designed to offer a very low current Power-down mode. The user can wake-up from SLEEP through external RESET, Watchdog Timer wake-up or through an interrupt. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select various options.

6.1 Configuration Bits

The configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space. In fact, it belongs to the special test/configuration memory space (2000h-3FFFh), which can be accessed only during programming.

NOTES:

BTFSS	Bit Test f, Skip if Set						
Syntax:	[label] B	TFSS f,l)				
Operands:	$0 \le f \le 12$ $0 \le b < 7$	7					
Operation:	skip if (f<	b>) = 1					
Status Affected:	None						
Encoding:	01	11bb	bfff	ffff			
Description:	If bit 'b' in register 'f' is '1' then the next instruction is skipped. If bit 'b' is '1', then the next instruction fetched during the current instruction execution, is discarded and a NOP is executed instead, making this a two-cycle instruction.						
Words:	1						
Cycles:	1(2)						
Example	HERE FALSE TRUE	BTFSS GOTO •	FLAG,1	S_CODE			
	Before In	struction					
	PC	= ad	dress нег	RE			
	0, Iress FAL 1, Iress TRU						

CALL	Call Subroutine							
Syntax:	[label] CALL k							
Operands:	$0 \le k \le 20$)47						
Operation:	(PC)+ 1 \rightarrow TOS, k \rightarrow PC<10:0>, (PCLATH<4:3>) \rightarrow PC<12:11>							
Status Affected:	None							
Encoding:	10	0kkk	kkkk	kkkk				
Description:	Call Subroutine. First, return address (PC+1) is pushed onto the stack. The eleven bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a two-cycle instruction							
Words:	1							
Cycles:	2							
Example	HERE	CALL	THERE					
	Before In:	struction						
	PC	= Add	lress her	E				
	After Instr	uction						
	PC	= Add	lress THE	RE				
	TOS	= Add	lress her	E+1				

CLRF	Clear f					
Syntax:	[label] (CLRF f	:			
Operands:	$0 \le f \le 12$	27				
Operation:	$00h \rightarrow (f)$ $1 \rightarrow Z$)				
Status Affected:	Z					
Encoding:	00	0001	1fff	ffff		
Description:	The conte	Ū	ster 'f' are	cleared		
Words:	1					
Cycles:	1					
Example	CLRF	FLAG_F	REG			
	Before In	struction G_REG=				
	After Instruction					
	FLA	G_REG=	0x00			
	Z	=	1			

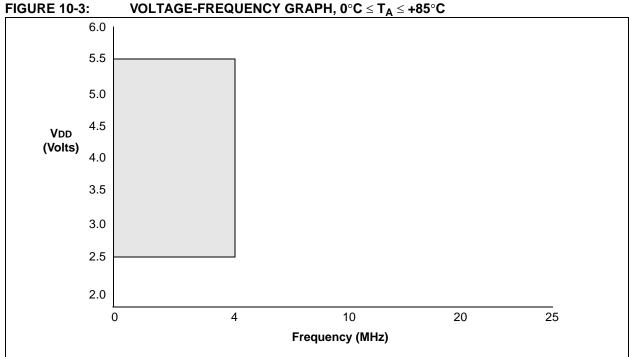
10.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings †

Ambient Temperature under bias	40° to +125°C
Storage Temperature	65° to +150°C
Voltage on any pin with respect to Vss (except VDD and MCLR)	0.6V to VDD +0.6V
Voltage on VDD with respect to Vss	0 to +7.5V
Voltage on MCLR with respect to Vss	0 to +14V
Total power Dissipation (Note 1)	1.0W
Maximum Current out of Vss pin	300 mA
Maximum Current into VDD pin	250 mA
Input Clamp Current, Iικ (VI < 0 or VI > VDD)	±20 mA
Output Clamp Current, IOκ (V0 < 0 or V0 > VDD)	±20 mA
Maximum Output Current sunk by any I/O pin	25 mA
Maximum Output Current sourced by any I/O pin	25 mA
Maximum Current sunk by PORTA, PORTB and PORTC	200 mA
Maximum Current sourced by PORTA, PORTB and PORTC	200 mA
Note 1. Power dissination is calculated as follows: Pais - Vpp v (lpp \subseteq [qui) \subseteq [(\lpha \)]	2 ((a) x (a)) 1 Z(((a) x (a))

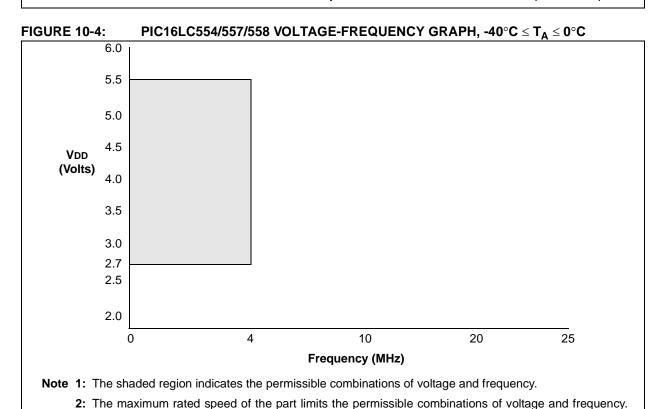
Note 1: Power dissipation is calculated as follows: PDIS = VDD x {IDD - Σ IOH} + Σ {(VDD-VOH) x IOH} + Σ (VOI x IOL)

† **NOTICE**: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.



Please reference the Product Identification System section for the maximum rated speed of the parts.

FIGURE 10-8: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

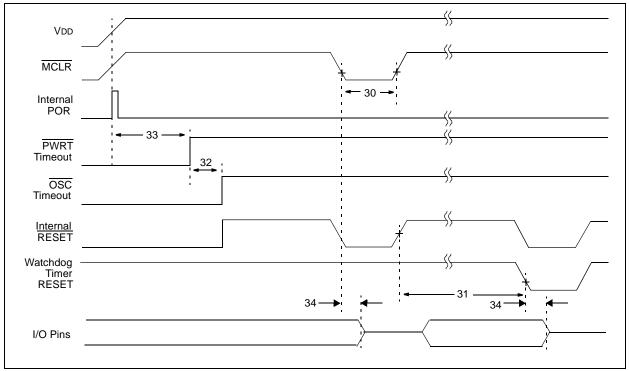


TABLE 10-3: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	2000	_	_	ns	-40° to +85°C
31	Twdt	Watchdog Timer Timeout Period (No Prescaler)	7*	18	33*	ms	$VDD = 5.0V, -40^{\circ} \text{ to } +85^{\circ}C$
32	Tost	Oscillation Start-up Timer Period	_	1024 Tosc	_	_	Tosc = OSC1 period
33	Tpwrt	Power-up Timer Period	28*	72	132*	ms	$VDD = 5.0V, -40^{\circ} \text{ to } +85^{\circ}C$
34	Tıoz	I/O hi-impedance from MCLR low			2.0*	μS	

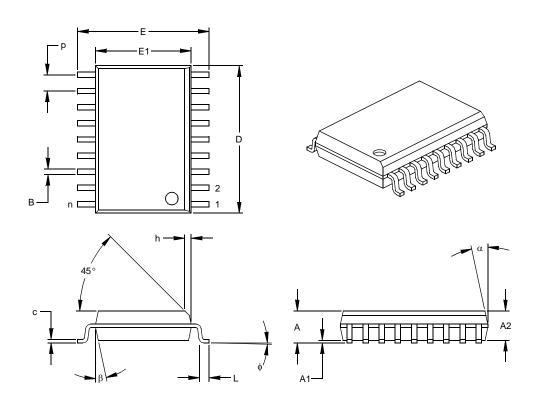
^{*} These parameters are characterized but not tested.

[†] Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

NOTES:

18-Lead Plastic Small Outline (SO) - Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		INCHES*		MILLIMETERS			
Dimensio	n Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	р		.050			1.27	
Overall Height	Α	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	Е	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	ф	0	4	8	0	4	8
Lead Thickness	С	.009	.011	.012	0.23	0.27	0.30
Lead Width	В	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed

Preliminary

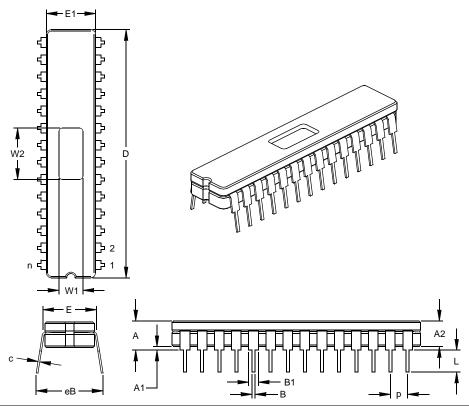
.010" (0.254mm) per side.

JEDEC Equivalent: MS-013 Drawing No. C04-051

^{*} Controlling Parameter § Significant Characteristic

28-Lead Ceramic Dual In-line with Window (JW) - 300 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		INCHES*		MILLIMETERS			
Dimension	MIN	NOM	MAX	MIN	NOM	MAX	
Number of Pins	n		28			28	
Pitch	р		.100			2.54	
Top to Seating Plane	Α	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	Е	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	1.430	1.458	1.485	36.32	37.02	37.72
Tip to Seating Plane	L	.135	.140	.145	3.43	3.56	3.68
Lead Thickness	С	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.058	.065	1.27	1.46	1.65
Lower Lead Width	В	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing §	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.290	.300	.310	7.37	7.62	7.87

 ^{*}Controlling Parameter
 \$ Significant Characteristic
 JEDEC Equivalent: MO-058
 Drawing No. C04-080

APPENDIX A: ENHANCEMENTS

The following are the list of enhancements over the PIC16C5X microcontroller family:

- Instruction word length is increased to 14 bits.
 This allows larger page sizes both in program memory (4K now as opposed to 512 before) and register file (up to 128 bytes now versus 32 bytes before).
- 2. A PC high latch register (PCLATH) is added to handle program memory paging. PA2, PA1, PA0 bits are removed from STATUS register.
- Data memory paging is slightly redefined. STATUS register is modified.
- 4. Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW.

 Two instructions TRIS and OPTION are being phased out although they are kept for compatibility with PIC16C5X.
- OPTION and TRIS registers are made addressable.
- Interrupt capability is added. Interrupt vector is at 0004h.
- 7. Stack size is increased to 8 deep.
- 8. RESET vector is changed to 0000h.
- RESET of all registers is revised. Three different RESET (and wake-up) types are recognized. Registers are reset differently.
- Wake-up from SLEEP through interrupt is added.
- 11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
- 12. PORTB has weak pull-ups and interrupt-onchange feature.
- 13. Timer0 clock input, T0CKI pin is also a port pin (RA4/T0CKI) and has a TRIS bit.
- 14. FSR is made a full 8-bit register.
- 15. "In-circuit programming" is made possible. The user can program PIC16C55X devices using only five pins: VDD, VSS, VPP, RB6 (clock) and RB7 (data in/out).
- 16. PCON status register is added with a Power-on Reset (POR) status bit.
- 17. Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
- 18. PORTA inputs are now Schmitt Trigger inputs.

APPENDIX B: COMPATIBILITY

To convert code written for PIC16C5X to PIC16C55X, the user should take the following steps:

- Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
- Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
- 3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
- 4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
- 5. Change RESET vector to 0000h.

APPENDIX C: REVISION HISTORY

Revision E (January 2013)

Added a note to each package outline drawing.

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